ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. I international and Par	PC. Bannockt	ourn. Illinois. A	ll rights reserved un tions.	nder both	This docum level parts, t	ent is a declaration entite decl	on of the substand acompasses all lo	ces within the manufacture wer level materials for w	rer listed it which the m	em. Note: it anufacturer	f the item is an as has engineering	sembly with lower responsibility.	
	1.1IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175xForr Dist				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Info				fg Informati	on			
Supplier Information													
Company name* Compan			ompany unique ID			Unique ID Authority				Response Date*			
onsemi										2025-05-14			
Contact Name Title - Contac			ontact			Phone - Contact*			Email - Contact*				
Product-Env-Stewards Product Envi			Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative			resentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product E			duct Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site	١	Weight*	UOM	Unit Type	
	NCV896	NCV896530MWTXG Dual 2.25 MI		MHz low voltage smps		2025-05-14				27.42	mg	Each	
Manufacturing Proccess Informa	tion		-					·				·	
Terminal Plating / Grid Array Ma	Terminal Plating / Grid Array Material Terminal Base		lloy J-STD-020 MSL Rating		L Rating	Peak Process Body Temperature Max Time at I		ature Max Time at Peak	k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	3	6		260	C	30	secon	ds 3			
Comments													
ATTENTION: MSL 3 Rated item require	s Bake and D	ry Pack (after	electrical test)										
for more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).								
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	stislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.98	mg	Supplier	Silicon (Si)	7440-21-3		1.98	mg
Die Attach	0.2	mg	Supplier	Silver (Ag)	7440-22-4		0.15	mg
			Supplier	Epoxy resins	129915-35-1		0.05	mg
Lead Frame	8.32	mg	Supplier	Silver (Ag)	7440-22-4		0.208	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0083	mg
			Supplier	Iron (Fe)	7439-89-6		0.1997	mg
			Supplier	Copper (Cu)	7440-50-8		7.904	mg
Mold Compound-Black	16.08	mg		Epoxy resin	proprietary data		0.7558	mg
			Supplier	Phenol Resin	Proprietary Data		0.7558	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0161	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		14.5524	mg
Plating	0.66	mg	Supplier	Tin (Sn)	7440-31-5		0.66	mg
Wire Bond - Au	0.18	mg	Supplier	Gold (Au)	7440-57-5		0.18	mg